

HVB350BYP

Silicon Epitaxial Planar Variable Capacitance Diode for VCO

REJ03G0487-0100

(Previous: ADE-208-1420)

Rev.1.00 Jan 11, 2005

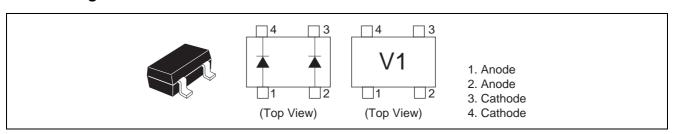
Features

- High capacitance ratio. (n = 2.8 min)
- Low series resistance. (rs = 0.5 max)
- Good C-V linearity.
- CMPAK-4 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVB350BYP	V1	CMPAK-4

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

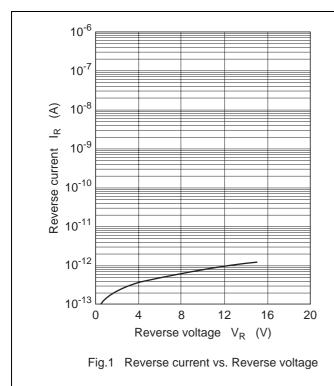
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 15 V
	I _{R2}	_	_	100		V _R = 15 V, Ta = 60°C
Capacitance	C ₁	15.5	_	17.0	pF	V _R = 1 V, f = 1 MHz
	C ₄	5.0	_	6.0		V _R = 4 V, f = 1 MHz
Capacitance ratio	n	2.8	_	_	_	C ₁ / C ₄
Series resistance	rs	_	_	0.5	Ω	V _R = 1 V, f = 470 MHz

Note: 1. Per one device.

Main Characteristic



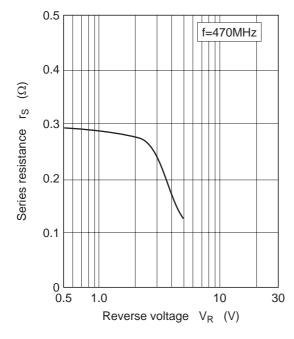


Fig.3 Series resistance vs. Reverse voltage

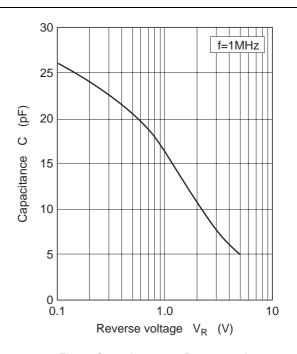


Fig.2 Capacitance vs. Reverse voltage

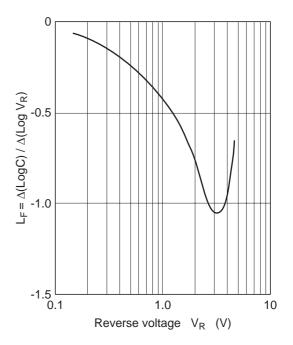
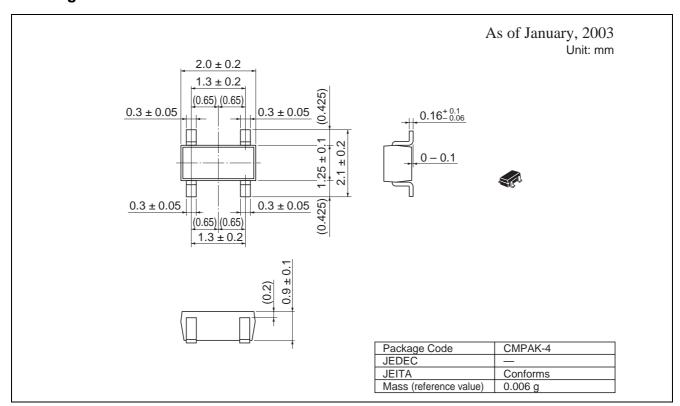


Fig.4 L_F vs. Reverse voltage

Package Dimensions



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